

NEW MODEL

Fully-Automatic Wafer Mounter

RAD-2510F/8



- ✓ Perfectly suited for SiC & GaN
- ⤵ High-speed operation
- ✂ Advanced inline pre-cut system
- ⊗ Supports warped wafer handling
- 👁 Built-in vision system



LINTEC Corporation

BENEFITS



High-speed operation

Operates at high speed with a capacity of 120 wafers/hour and includes an improved attachment table heating function.



Supports warped wafer handling

The non-contact alignment system enables the handling of 200 mm wafers with up to 5mm warpage.



Built-in vision system

Optionally, the machine can incorporate an integrated vision system to facilitate closed-loop process control (wafer ID reader & barcode attachment system).



Small foot print

Compact design to save valuable clean-room space.



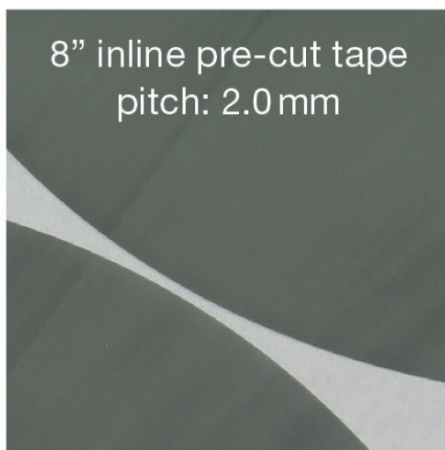
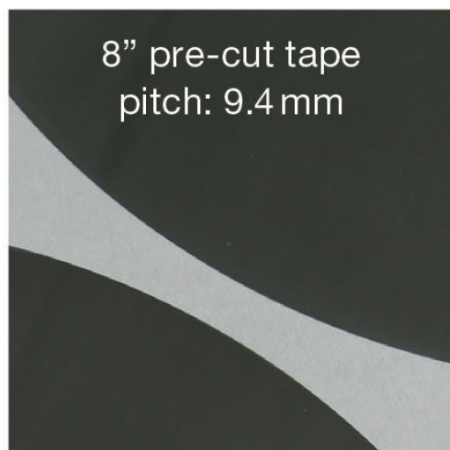
RING-FRAME STOCKER

- Storage of up to 300 ring-frames (steel)
- Automated frame lift-up by vacuum-gripper
- Reduced operator time



INLINE PRE-CUT SYSTEM

- Reduced tape pitch from 10mm to 2mm
- Minimized waste of material, decreased production cost
- Available as an option



SPECIFICATION

Wafer size	200mm, 150mm, 125mm, 100mm
Ring frame size	200mm, 150mm
Equipment size	1,360mm (W) x 1,830mm (D) x 1,800mm (H)
Weight	1,500kg
UPH	120 wafers/hour* *Capacity based on following conditions: Wafer: 200mm non-polished mirror wafer. Dicing tape: G-11D from LINTEC

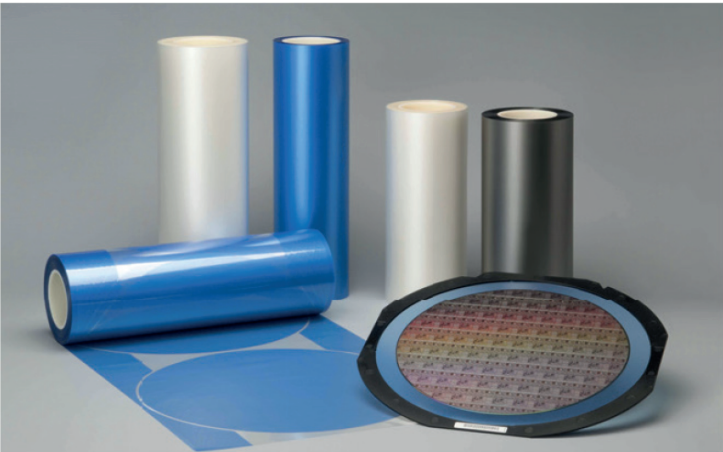
SUITABLE TAPES

The machine is capable to process the following types of Adwill tape:

- Dicing tape: Adwill D series & G series
- Dicing die bonding tape: Adwill LE tape
- Backside coating tape: Adwill LC pre-cut tape

OUR RECOMMENDATION

For SiC & GaN dicing:
Adwill D-175D*, Adwill D-485H





STANDARD

- Non-contact wafer-aligner
- Non-contact wafer mounting table
- Single loader & unloader



OPTIONS

- Full-contact wafer mounting table
- Wafer & mounting table cleaning-function
- Double loader & unloader specification
- Dicing tape inline pre-cut unit
- Attachment table heater specification
- Vision system (wafer ID reader & barcode attachment system)
- Host communication function (SECS/GEM)
- ESD compatibility



Adwill

Tape x Equipment

Contact us.
We look forward
to meeting you!



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